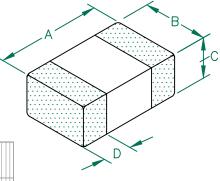
## CPI1008K1R0R-10

## PHYSICAL DIMENSIONS:

D 0.60 [.024] + 0.20[.008]



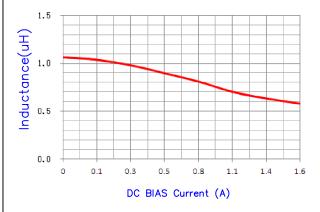
ELECTRICAL CHARACTERISTICS:									
	L (μΗ) @ 1MHz ± 20%	DCR ( $\Omega$ )	l (Max)						
Nom	1.0								
Min	0.8								
Max	1.2	0.1375	1600mA						

NOTES: UNLESS OTHERWISE SPECIFIED

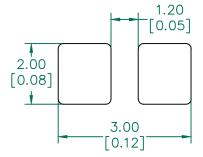
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. OPERATION TEMPERATURE TEMP: -55°C~+125°C

# 2.5 Ls vs Frequency 2.5 2.0 1.5 1.0 0.5 1 10 100 1,000 Frequency (MHz)

Ls vs DC BIAS Current



### LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [0.030] to this dimension)

## REFLOW SOLDERING 250 PRE-HEATING [482] 200 [392] 200 [392] 90 SECONDS SOLDERING 255 ± 5°C NATURAL COOLING 90 SECONDS

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird				
				Tech. and is loaned in confidence subject to return upon request with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.	nd	Laird		
				PROJECT/PART NUMBER:	REV	PART TY	PE:	DRAWN BY:
С	UPDATE PAD DIMENSION ROHS	07/08/14	QU	CPI1008K1R0R-10	С	C CO-FIRE		QU
B	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU	DATE: 03/01/11 SC	ALE: N	E: NTS SHEET:		
	ODIOINAL DOAFT	03/01/11	OII.	7 00/01/11	IN	'''		
A	ORIGINAL DRAFT	03/01/11	QU	CPI1008K1R0R-10-C	OOL #			of 1

60 SECONDS